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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/748,652	12/30/2003	Geon-Ook Park	20067/OPP031475US	6900	
34431 7:	590 11/22/2005	EXAMINER			
HANLEY, FI	LIGHT & ZIMMERN	TOBERGTE, 1	TOBERGTE, NICHOLAS J		
20 N. WACKE SUITE 4220	R DRIVE	ART UNIT	PAPER NUMBER		
CHICAGO, IL	60606	2823			

DATE MAILED: 11/22/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		Ar	oplication No.	Applicant(s)			
		10	0/748,652	PARK, GEON-OO	ok mi		
Office Action Summary			caminer	Art Unit			
		Ni	cholas J. Tobergte	2823			
 Period for	The MAILING DATE of this commun Reply	ication appears	s on the cover sheet with the c	orrespondence ad	ldress		
WHICH - Extensi after SI - If NO po - Failure Any rep	RTENED STATUTORY PERIOD F IEVER IS LONGER, FROM THE N ons of time may be available under the provisions X (6) MONTHS from the mailing date of this commerciod for reply is specified above, the maximum storeply within the set or extended period for reply by received by the Office later than three months patent term adjustment. See 37 CFR 1.704(b).	ALLING DATE of 37 CFR 1.136(a). nunication. atutory period will ap will, by statute, caus	OF THIS COMMUNICATION In no event, however, may a reply be tirely and will expire SIX (6) MONTHS from the application to become ABANDONE	N. mely filed n the mailing date of this co ED (35 U.S.C. § 133).			
Status							
1)⊠ 6	Responsive to communication(s) file	ed on 16 Nove	mber 2005.				
•	•		ion is non-final.				
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closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.							
Dispositio	n of Claims						
5)□ C 6)図 C 7)図 C	Claim(s) <u>1-8</u> is/are pending in the application of the above claim(s) is/acceptaim(s) is/acceptaim(s) is/are allowed. Claim(s) <u>1-3</u> is/are rejected. Claim(s) <u>4-8</u> is/are objected to. Claim(s) are subject to restrict	ire withdrawn f					
Applicatio	n Papers						
9)∏ Ті	ne specification is objected to by th	e Examiner.					
•—	ne drawing(s) filed on is/are		ed or b) objected to by the	Examiner.			
A	pplicant may not request that any obje	ction to the drav	ving(s) be held in abeyance. Se	e 37 CFR 1.85(a).			
	eplacement drawing sheet(s) including the oath or declaration is objected t	_					
Priority un	der 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  a) All b) Some * c) None of:  1. Certified copies of the priority documents have been received.  2. Certified copies of the priority documents have been received in Application No.  3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  * See the attached detailed Office action for a list of the certified copies not received.							
2) Notice 3) Informa	of References Cited (PTO-892) of Draftsperson's Patent Drawing Review (International Disclosure Statement(s) (PTO-1449 on No(s)/Mail Date 3/1/04. 4/18/05		4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:	oate	O-152)		

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#### **DETAILED ACTION**

### Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1 and 2 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kim (US 6,008,526) and further in view of Kao et al (US 20030170964 A1).

Pertaining to claims 1 and 2, <u>Kim</u> teaches a method for forming a trench in a semiconductor device comprising:

forming a pad oxide film 2 and a silicon nitride film 4 on a semiconductor substrate 1;

selectively etching the silicon nitride film 4 and the pad oxide film 2 on a region to be formed with a trench Col 2 lines 28-31;

implanting oxygen ions into the semiconductor substrate in the region to be formed with the trench Col 3 lines 50-56;

forming an oxide in the semiconductor substrate by reacting the oxygen ions with the semiconductor substrate through a thermal diffusion of the oxygen ions **Col 3 lines**42-48:

forming the trench by etching the semiconductor substrate and the oxide on the region to be formed with the trench Col 2 lines 26-31 and Fig 2B;

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forming a liner oxide film 8 on an inner wall of the trench using a thermal diffusion process Col 2 lines 34-35; and

forming an insulation film 10 on the liner oxide film such that the trench is filled Col 2 lines 35-37.

<u>Kim</u> fails to teach the method of claim 1 wherein the mask used in the etch is the silicon nitride film.

<u>Kim</u> fails to teach the method of claim 2 wherein the substrate is comprised of a silicon substrate.

<u>Kao</u> teaches the use of a silicon nitride mask when etching a trench in an ion implanted semiconductor substrate. **[0027-0033]**. Therefore it would be obvious to one of ordinary skill in the art to apply the teachings of <u>Kao</u> to the process of <u>Kim</u>. The motivation for doing this would be to decrease the number of photoresist masking layers as well as utilize a mask that is impermeable to implanted ions such as a silicon nitride mask **[0033]**.

<u>Kao</u> teaches the use of a silicon substrate **[0025]**. <u>Kao</u> discloses that silicon is a typical semiconductor substrate material, and therefor would be obvious to one of ordinary skill in the art to choose such a well known and obvious material in the art.

Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over <u>Kim</u> (US 6,008,526) and further in view of <u>Kao et al</u> (US 20030170964 A1).

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<u>Kim</u> teaches the method of claim 2, wherein, in selectively etching the oxidation blocking layer **34** and the pad oxide film **32**, a first photosensitive film pattern **36** for exposing the oxidation blocking layer on the region to be formed with the trench is formed by applying, exposing, and developing a photosensitive film on the oxidation blocking layer, and then the oxidation blocking layer and the pad oxide film exposed are selectively etched using the first photosensitive film pattern as a mask **See Fig 4A**.

<u>Kim</u> fails to explicitly point out that silicon nitride is an oxidation blocking layer.

<u>Kao</u> teaches that silicon nitride is used as an oxidation blocking layer [0033].

Therefor it would be obvious to one of ordinary skill in the art to expose the trench using a photosensitive film on the oxidation blocking layer (silicon nitride film) and the pad oxide layer, the motivation being that this is a conventional photolithography process known in the art.

## Allowable Subject Matter

Claims 4-8 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The reason for allowance is that it is not obvious, based on the prior art, to form a second photosensitive film pattern before ion implantation that is narrower then the first photosensitive film pattern.

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#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nicholas J. Tobergte whose telephone number is 571-272-6006. The examiner can normally be reached on Mon - Thur 7am - 5:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew Smith can be reached on 571-272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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W. DAVID COLEMAN PRIMARY EXAMINER Page 5